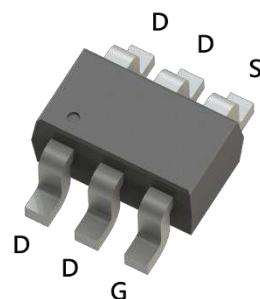


## P-Channel Enhancement Mode MOSFET

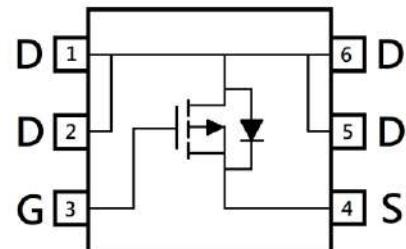
### Features:

- Low On Resistance
- Low Gate Charge
- Fast Switching Characteristic

SOT-26



$BV_{DSS}$	-150V
$I_D @ V_{GS} = -10V, T_A = 25^\circ C$	-0.95A
$R_{DS(ON)} \text{ typ.} @ V_{GS} = -10V, I_D = -1A$	555m $\Omega$



G : Gate S : Source D : Drain

### Ordering Information

Device	Package	Shipping
KTTF1P15A	SOT-26 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel



### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	$V_{DS}$	-150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current @ $V_{GS}=-10\text{V}$ , $T_A=25^\circ\text{C}$	$I_D$	-0.95	A
Continuous Drain Current @ $V_{GS}=-10\text{V}$ , $T_A=70^\circ\text{C}$		-0.76	
Pulsed Drain Current	$I_{DM}$	-3.8	
Continuous Body Diode Forward Current @ $T_A=25^\circ\text{C}$	$I_S$	-0.95	
Total Power Dissipation	$T_A=25^\circ\text{C}$	1.5	W
	$T_A=70^\circ\text{C}$	1	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	°C

### Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-ambient	$R_{\theta JA}$	85	°C/W

Note:

\*a. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR -4 board with 2 oz. copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The power dissipation  $P_D$  is based on  $R_{\theta JA}$  and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

\*b. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ . Ratings are based on low frequency and low duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

### **Electrical Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise specified)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
<b>Static</b>						
BV <sub>DSS</sub>	-150	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	
V <sub>GS(th)</sub>	-2	-	-4		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	
G <sub>FS</sub>	-	2.4	-	S	V <sub>DS</sub> =-10V, I <sub>D</sub> =-1A	
I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	
I <sub>DSS</sub>	-	-	-1	μA	V <sub>DS</sub> =-120V, V <sub>GS</sub> =0V	
R <sub>DSS(ON)</sub>	-	555	820	mΩ	V <sub>GS</sub> =-10V, I <sub>D</sub> =-1A	
<b>Dynamic</b>						
C <sub>iss</sub>	-	480	-	pF	V <sub>DS</sub> =-75V, V <sub>GS</sub> =0V, f=1MHz	
C <sub>oss</sub>	-	28	-			
C <sub>rss</sub>	-	22	-			
Q <sub>g</sub> *1, 2	-	11	-	nC	V <sub>DS</sub> =-75V, I <sub>D</sub> =-1A, V <sub>GS</sub> =-10V	
Q <sub>gs</sub> *1, 2	-	2.6	-			
Q <sub>gd</sub> *1, 2	-	2.6	-			
t <sub>d(ON)</sub> *1, 2	-	9.8	-	ns	V <sub>DS</sub> =-75V, I <sub>D</sub> =-1A, V <sub>GS</sub> =-10V, R <sub>GS</sub> =6Ω	
t <sub>r</sub> *1, 2	-	17	-			
t <sub>d(OFF)</sub> *1, 2	-	32	-			
t <sub>f</sub> *1, 2	-	28	-			
<b>Source-Drain Diode</b>						
V <sub>SD</sub> *1	-	-0.77	-1.2	V	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V	
tr	-	28	-	ns	I <sub>F</sub> =-1A, dI <sub>F</sub> /dt=100A/μs	
Qrr	-	33	-			

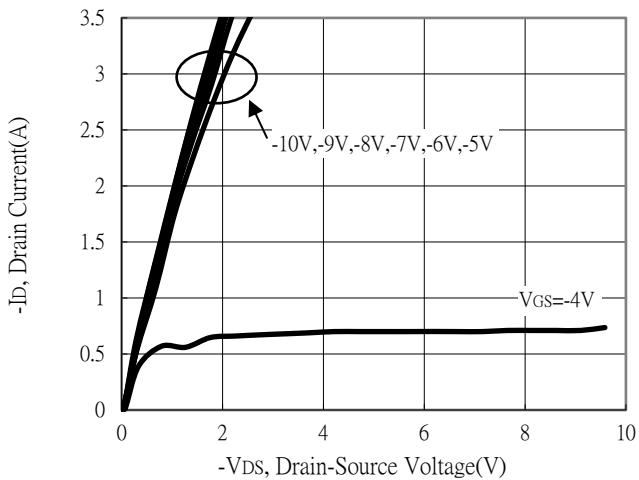
Note:

\*1. Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

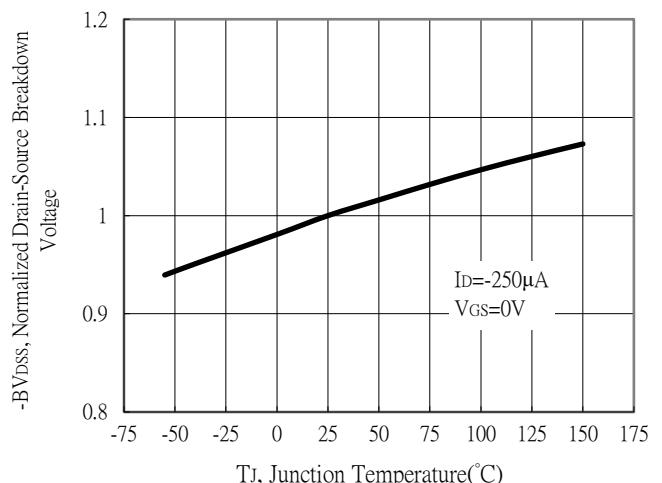
\*2. Independent of operating temperature

## Typical Characteristics

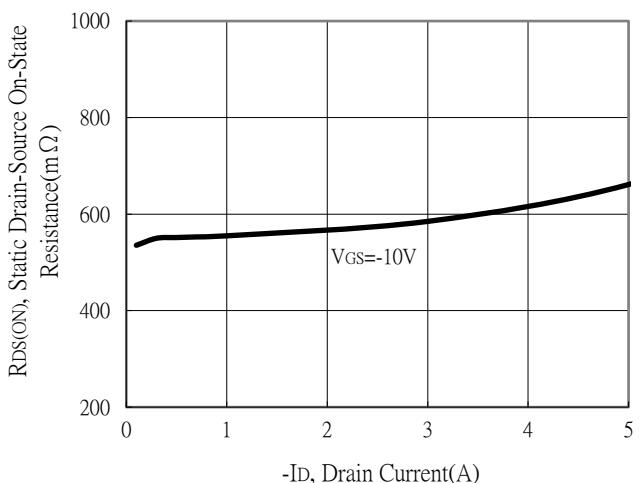
Typical Output Characteristics



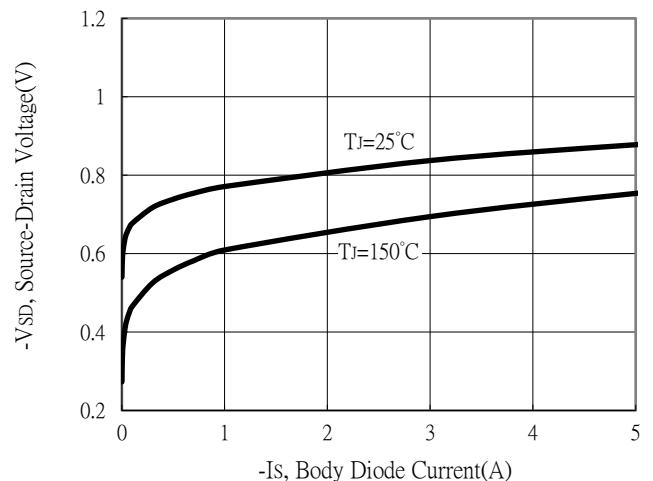
Breakdown Voltage vs Ambient Temperature



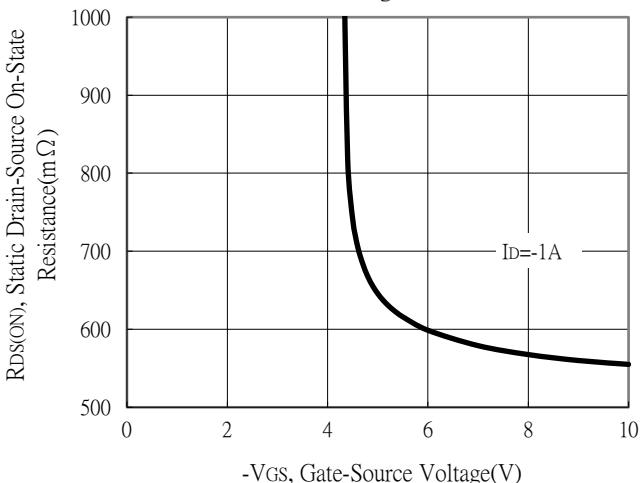
Static Drain-Source On-State resistance vs Drain Current



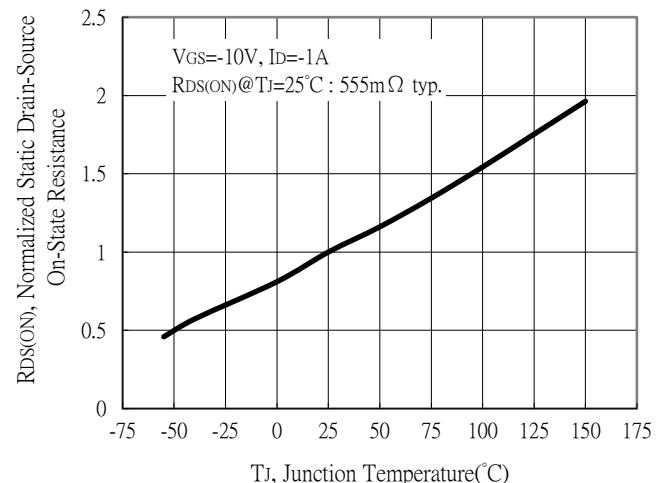
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

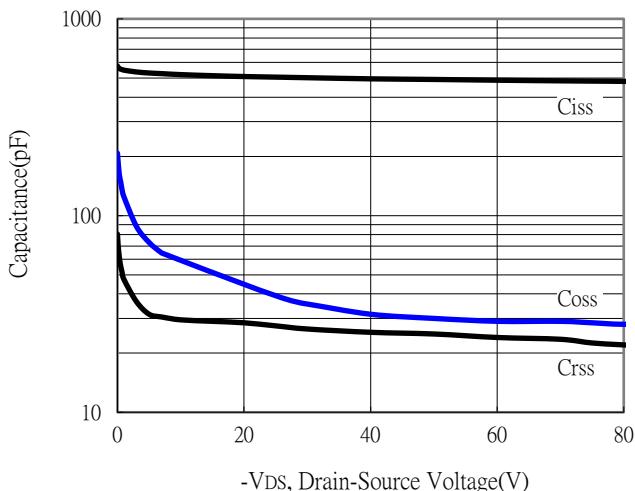


Drain-Source On-State Resistance vs Junction Temperature

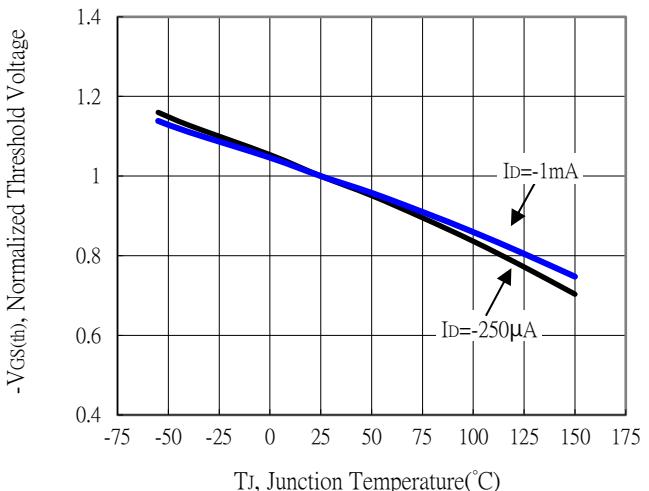


## Typical Characteristics (Cont.)

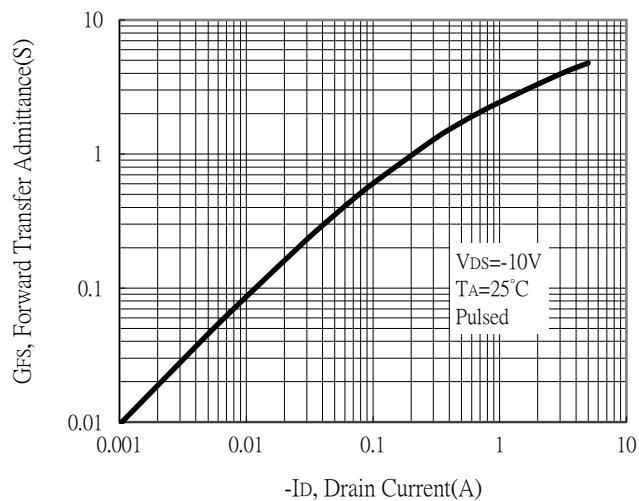
Capacitance vs Drain-to-Source Voltage



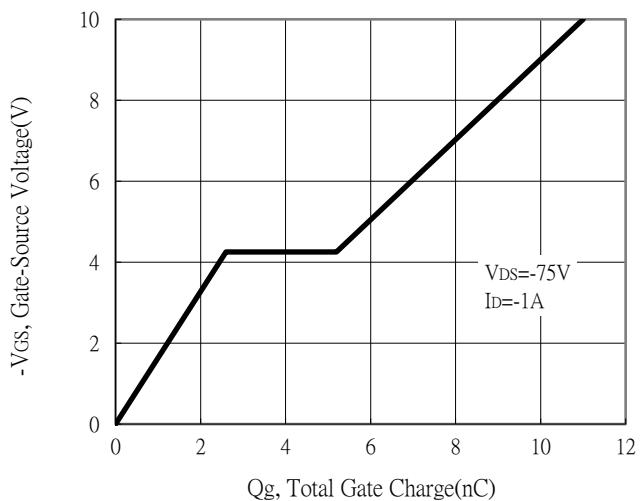
Threshold Voltage vs Junction Temperature



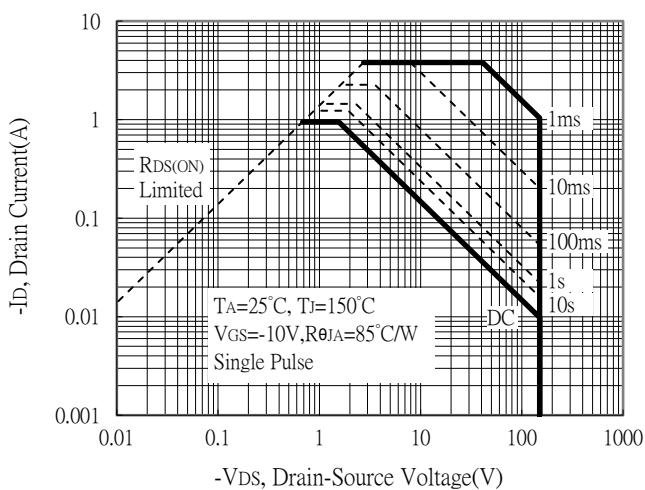
Forward Transfer Admittance vs Drain Current



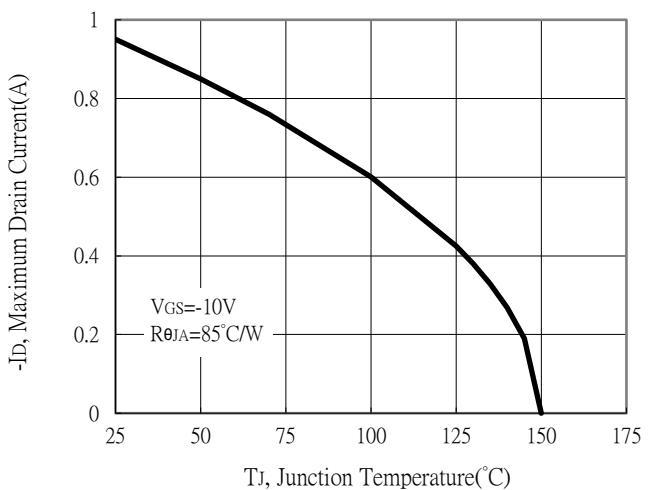
Gate Charge Characteristics



Maximum Safe Operating Area

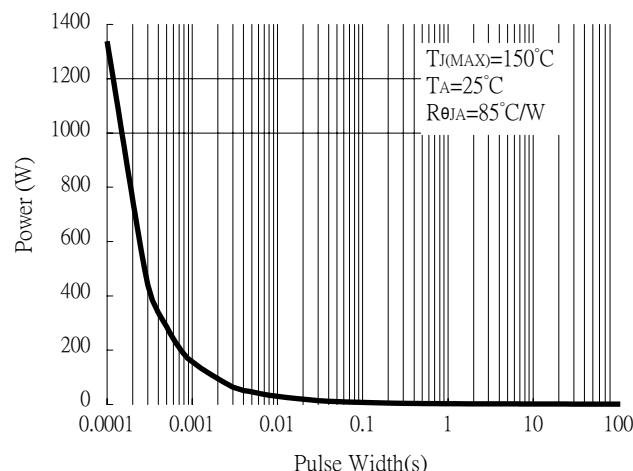


Maximum Drain Current vs Junction Temperature

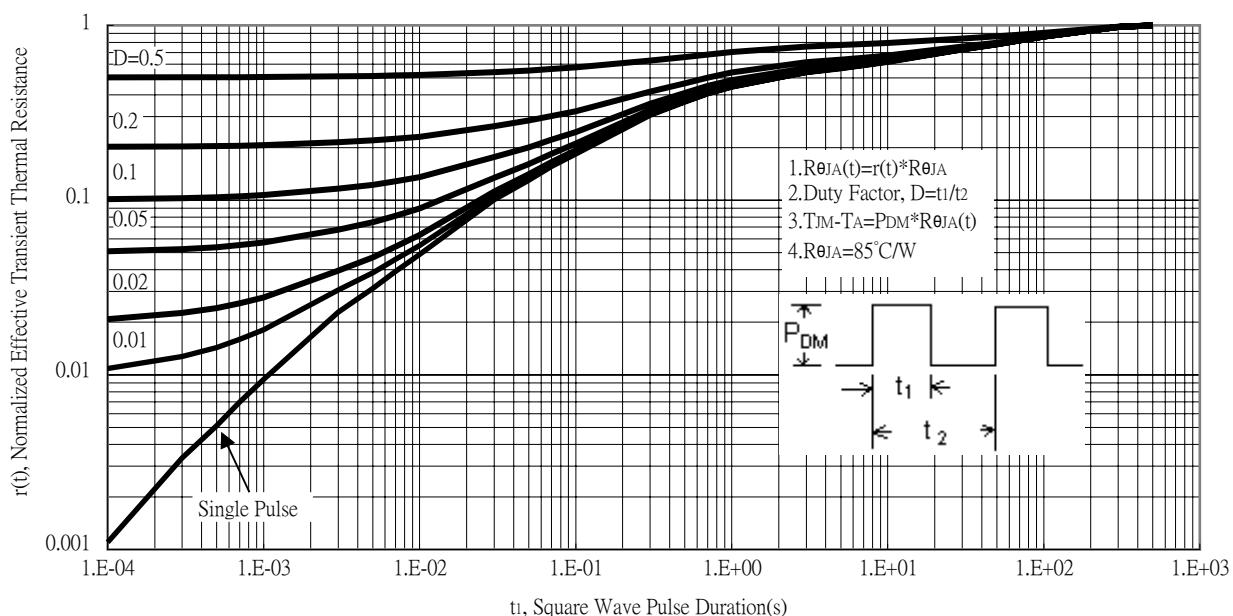


## Typical Characteristics (Cont.)

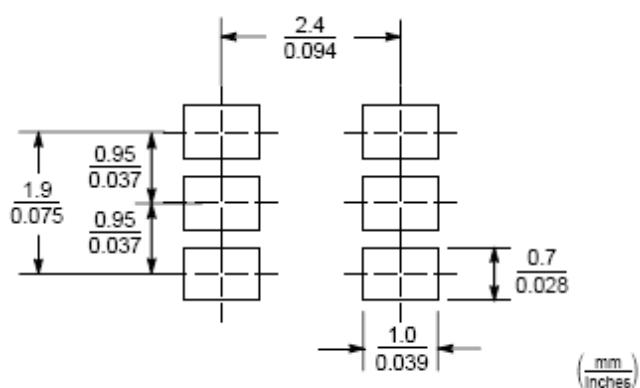
Single Pulse Power Rating, Junction to Ambient



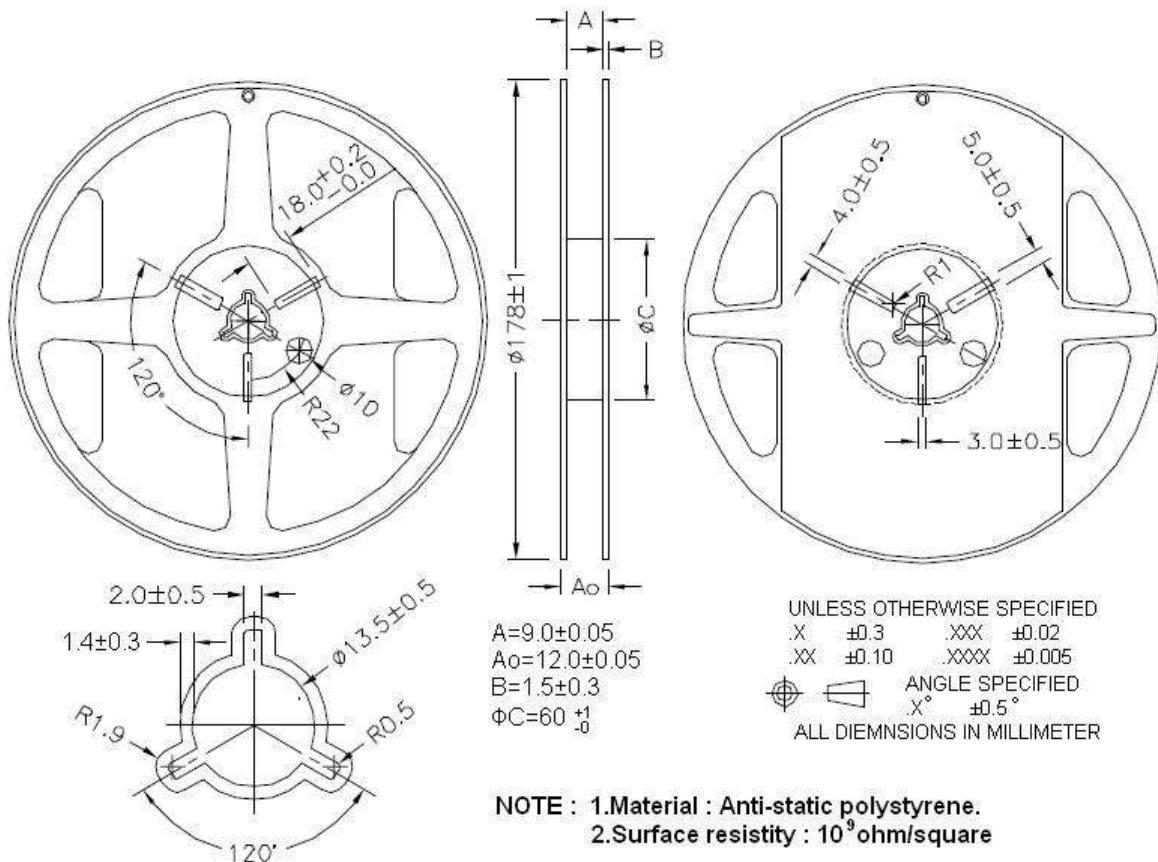
Transient Thermal Response Curves



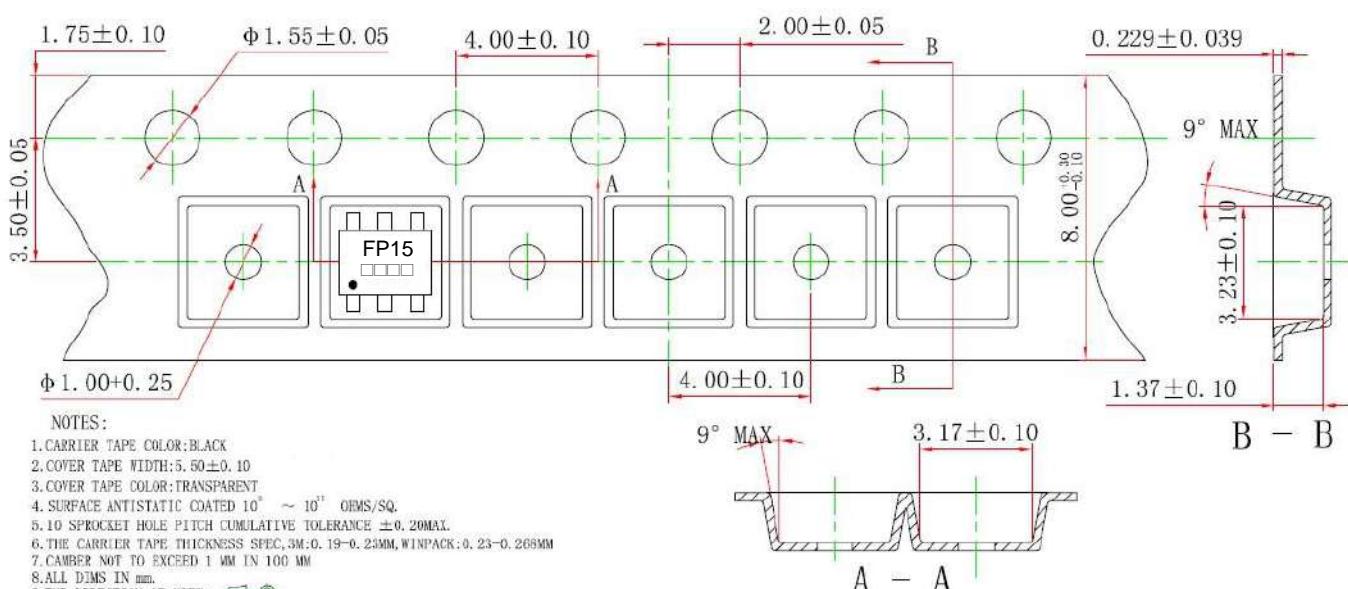
## Recommended Soldering Footprint



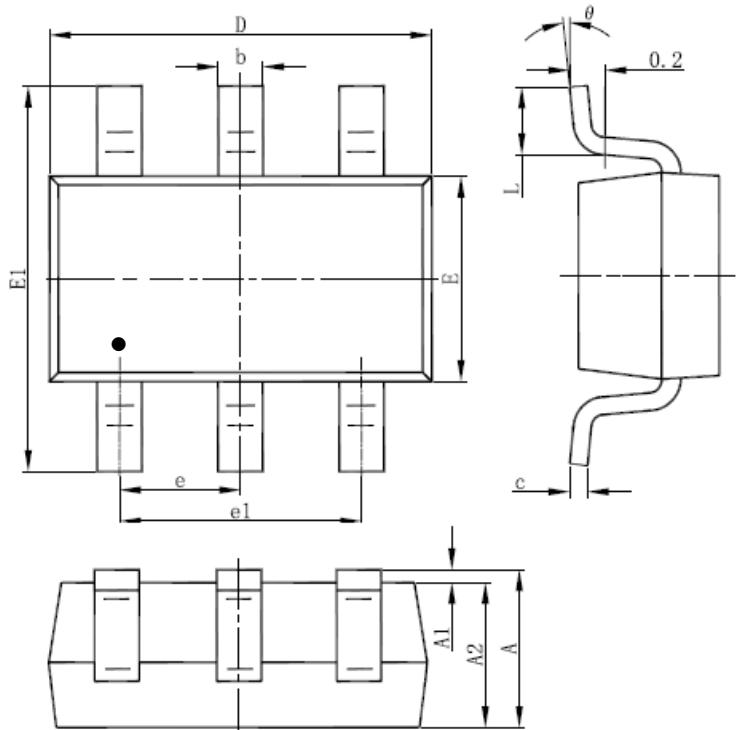
## Reel Dimension



## Carrier Tape Dimension

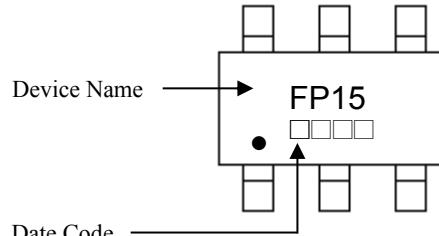


## SOT-26 Dimension



6-Lead SOT-26 Plastic  
Surface Mounted Package

Marking:



Style:

- Pin 1. Drain (D)
- Pin 2. Drain (D)
- Pin 3. Gate (G)
- Pin 4. Source (S)
- Pin 5. Drain (D)
- Pin 6. Drain (D)

Date Code(counting from left to right) :

1<sup>st</sup> code: year code, the last digit of Christian year  
 2<sup>nd</sup> code : month code, Jan→A, Feb→B, Mar→C,

Apr→D, May→E, Jun→F, Jul→G, Aug→H,  
 Sep→J, Oct→K, Nov→L, Dec→M

3<sup>rd</sup> and 4<sup>th</sup> codes : production serial number, 01~99

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049	E	1.500	1.700	0.059	0.067
A1	0.000	0.100	0.000	0.004	E1	2.650	2.950	0.104	0.116
A2	1.050	1.150	0.041	0.045	e	0.950 (BSC)		0.037 (BSC)	
b	0.300	0.500	0.012	0.020	e1	1.800	2.000	0.071	0.079
c	0.100	0.200	0.004	0.008	L	0.300	0.600	0.012	0.024
D	2.820	3.020	0.111	0.119	θ	0°	8°	0°	8°